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Accessing ratios of quantized resistances in graphene *p-n* junction devices using multiple terminals

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ABSTRACT 17

18 The utilization of multiple current terminals on millimeter-scale graphene p-n junction devices has enabled the measurement of many atyp-19 ical, fractional multiples of the quantized Hall resistance at the v = 2 plateau ($R_{\rm H} \approx 12\,906\,\Omega$). These fractions take the form $\frac{a}{L}R_{\rm H}$ and can be determined both analytically and by simulations. These experiments validate the use of either the LTspice circuit simulator or the analytical 20 framework recently presented in similar work. Furthermore, the production of several devices with large-scale junctions substantiates the 21 22 approach of using simple ultraviolet lithography to obtain junctions of sufficient sharpness.

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26 Graphene, composed of carbon atoms arranged in a two-27 dimensional honeycomb lattice, has been extensively studied for 28 more than a decade, in part because of its excellent optical, mechan-29 ical, and electrical transport properties.¹⁻⁴ The quantum Hall effect (QHE) in graphene gives resistance values at $\frac{1}{(4n+2)}\frac{h}{e^2}$, where n 30 31 is an integer, h is the Planck constant, and e is the elementary 32 charge. Graphene p-n junctions (pnJs), which are suitable for one 33 to explore transport in the QHE,⁵⁻¹⁸ enable one to access vari-34 ous multiples and fractions of the von Klitzing constant. These 35 types of graphene devices also have additional applications in electron optics, photodetection,^{23–27} and quantum Hall resistance 36 37 standards.

38 For clarity, a pnJ device contains some form of interface at 39 which a positively doped and a negatively doped region meet. 40 For graphene, whose Fermi level can be electrically or chemically modulated, such an interface can be effectively one-dimensional, allowing edge state electrons to tunnel from one region to the other. This behavior results in the observation of quantized longitudinal resistances due to the presence of the junction. Typically, these devices are of sub-millimeter sizes due to constraints on top-gating. One motivation for pursuing large-scale pnJ devices is to determine the feasibility of using quantum transport across the junctions to access different quantized values of resistance, as shown in previous studies.³⁹⁻⁴¹ One first major hurdle is to fabricate large-**Q**349 scale devices without the need for top-gating, since such techniques become more complicated as the device incorporates more elements. Although extensive analyses exist on Landauer-Büttiker edge state equilibration,^{5–8,42–46} creating a *pnJ* device capable of accessing different plateaus with top gates is a difficult task. Instead, one approach to accessing different quantized values is to incorporate multiple

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current terminals, which opens the parameter space within which*pnJ* devices are able to be operated.

For millimeter-scale device fabrication, epitaxial graphene (EG) 58 59 is grown to accommodate device size, but the issue of processing the correspondingly large *pnJs* was not trivial, as shown in previous 60 work.47 This work elaborates on further efforts involving the use of 61 62 standard ultraviolet photolithography (UVP) and ZEP520A to build 63 pnJs having widths smaller than 200 nm. Devices were verified via 64 quantum Hall transport measurements and LTspice current simulations,⁴⁸ and multiple current terminals and configurations were 65 66 used to test the viability of the simulations as well as the quality of 67 the devices. Furthermore, recently reported analytical methods were 68 also used to predict atypical fractions of the quantized Hall resis-69 tance, R_H , that would become experimentally accessible depending on the configuration of the current terminals.⁴⁹ These exper-70 71 iments also serve as supporting evidence on the validity of those 72 analytical methods, which provide easily implementable algorithms 73 for determining effective quantized resistances in complicated pnJ 74 circuits.

Simulations for the *pn*J devices were performed with the ana log electronic circuit simulator LTspice in an identical manner as
 demonstrated for similar devices in other works.^{47,49-51} The circuit

uses both *p*-type and *n*-type *k*-terminal quantum Hall elements, des-78 ignated as either having ideal counterclockwise (CCW) or clockwise 79 (CW) edge state current flow. EG on SiC was fabricated into pnJ 80 devices after the growth at a temperature of 1900 °C. First, chips 81 were diced from 4H-SiC(0001) wafers (CREE)⁴⁸ and chemically 82 cleaned with a 5:1 diluted solution of hydrofluoric acid and deion-83 ized water. Just prior to growth, chips were processed with AZ5214E 84 to utilize polymer-assisted sublimation.³² Finally, after placing the chips on a polished graphite substrate (SPI Glas 22)⁵⁰ silicon-face **Q**485 86 down, the growth occurred under an ambient argon environment at 87 1900 °C with a graphite-lined resistive-element furnace (Materials 88 Research Furnaces, Inc.).⁴⁸ The corresponding heating and cooling 89 rates of the furnace were about 1.5 °C/s. 90

Once grown, EG was assessed with confocal laser scanning, optical, and atomic force microscopy (AFM).⁵³ Images acquired from these techniques are provided in Fig. 1, which confirmed that homogeneous monolayer EG had successfully covered millimeterscale areas (see the supplementary material for additional AFM images). Next, using Pd and Au as protective layers against organic contamination, photolithographic processes were performed, details of which may be found in other works.^{31,47} Once each Hall bar device was completed, it underwent Cr(CO)₃ functionalization to reduce



FIG. 1. (a) An illustration of the surface of an EG pnJ device. The photoresist S1813 was deposited and lithographically processed on specific regions where n-type doping was preferred. The molecule in ZEP520A is shown to clarify the electron acceptor as the photoresist is exposed to ultraviolet light. Cr(CO)₃ was used to stabilize the electron density. (b) A confocal microscope image acquired for the full device after wire bonding, with the darker region indicating the desired n-type regions. (c) A magnification of the small green box in (b) for a scale of the order of 5 µm. Oxidized residue from the Cr(CO)₃ deposition takes the form of visible black specs. (d) and (e) show both the two-dimensional and one-dimensional height profiles, respectively, with the one-dimensional profile represented as a white line in (d) and the two-dimensional profile acquired within the red box in (b).

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the electron density to approximately 10^{10} cm⁻².^{54–58} The major final steps included the deposition of S1813 photoresist as a spacer layer for intended *n*-type regions, PMMA/MMA photoresist as an additional spacer, and ZEP520A as a photoactive layer, as described in the literature.^{47,59} Uniformity is also verified with Raman spectra (see the supplementary material).

129 Although AFM images suggest a sloped S1813 spacer layer, 130 preservation of the *n*-type regions can still be accomplished with thicknesses of the order of 100 nm.⁴⁹ Furthermore, the upper bound 131 of the junction width resulting from these photolithographic pro-132 133 cesses was measured to be approximately 200 nm in another work, 134 rendering them of sufficient sharpness to accommodate edge-state propagation.⁴⁹ Ultraviolet (UV) light, with a wavelength of 254 nm, 135 136 was used to realize p-type doping in regions without \$1813. The lon-137 gitudinal resistivity was monitored during periods of UV exposure, 138 and additional information and data on this process are found in the supplementary material. 139

Completed four-junction devices, like the one shown in 140 141 Fig. 1(c), were measured with the traditional methods to verify 142 that regions exhibited resistance quantization. This type of device is shown in Fig. 2(a). Electrical contact pads are numbered based on 143 144 the measurement system used to provide the corresponding mea-145 surements in (b) and (c). Traditional longitudinal and Hall mea-146 surements were acquired at 1.6 K and ± 9 T, with the results shown 1476 in Fig. 2(b) as black and red curves, respectively. With proper UV exposure, regions without the S1813 spacer layer are subject to *p* doping, and after sufficient exposure time, they become set as *p*-type regions. 150

The resulting *pn*Js were found to be of sufficient narrowness to accommodate dissipationless edge-state propagation.⁴⁷ However, to further verify that the entire device was functional, voltage measurements were performed along the length of the device, bearing in mind the formation of the device's so-called hot spots, as shown pictorially in Ref. 40. In Fig. 2(*c*), the plotted resistances further support the idea that millimeter-scale *pn*Js can be successfully fabricated with standard UV lithography.

A recent formulation for using multiple terminals on a *pnJ* device as the only resistive elements of a circuit has established a mathematical way of predicting the effective quantized resistance of that circuit.⁴⁹ Essentially, a single current source can inject current into an arbitrary number of terminals—likewise for the drain port of the current source. The voltage difference of the whole circuit, and by extension the effective quantized resistance $R_{\text{eff}} = q_{N-1}R_{\text{H}}$, can then be measured between just after the current source starts and just before the drain of the current source terminates. The coefficient of effective resistance (CER) is labeled *q* and represents a device configuration containing *N* total terminals that are used (either as a source or as a drain).

Eight different configurations were measured, and their effective circuit resistances are plotted in Fig. 3. Furthermore, two meth-



173 FIG. 2. (a) A four-junction device illustration with numbers corresponding to 174 175 wired connections on a 32-pin leadless chip carrier, with the electron flow enter-176 177 ing from the right-side contact (drain) and with the source on the left side. A cur-178 179 rent of 1 µA was applied for all measurements. Darker and lighter gray col-180 ors indicate p-type and n-type regions, 181 182 respectively. The three middle regions are tested to check traditional Hall resis-183 tance curves, with orange and cyan p 184 185 labels matching those seen in (b). (b) The longitudinal and Hall resistances 186 187 were measured from 9 T to -9 T at 188 1.6 K and are represented by red and 189 black curves, respectively. Pin labels are 190 also provided. (c) Integer multiples of $R_{\rm H}$ (from 1 to 5) were measured across 191 varying lengths of the device to ensure 192 device functionality. Dotted lines are pro-193 194 vided as a visual guide to compare exact quantized values. All regions were on the 195 v = 2 plateau. 196

FIG. 3. Multiple-terminal configurations 197 have been measured and their effec-198 tive circuit resistances are plotted in the 199 four panels. Three of the four panels 200 contain four-terminal configurations (two 201 sources and two drains), whereas the 202 panel on the lower left corner uses a five-203 terminal and an eight-terminal configu-204 ration. The latter panel, when compared 205 with the calculated and simulated value 206 in dotted gray lines, provides some evi-207 dence that the CER formulation is valid 208 for larger numbers of used terminals. All 209 panels contain the calculated and sim-210 ulated value in dotted gray lines (valid 211 for sufficiently high magnetic flux den-212 sity), and for all cases, the calculated and 213 simulated results agree with each other. 214 The insets of each panel have colored 215 perimeters corresponding to the curve of 216 the same color and illustrate the four-217 junction device and its edge-state current 218 flow abstractly. The blue plus and red 219 minus signs indicate source and drain 220 terminals, respectively. 221

FIG. 4. (a) A seven-junction device illus-222 tration with numbers corresponding to 223 the same measurement system is shown 224 using a measurement current of 1 μ A. 225 Darker and lighter gray colors indicate 226 p-type and n-type regions, respectively. 227 Each measurement pair is color-coded 228 for easy comparison to its correspond-229 ing data. (b) The resistance is plotted for 230 each of the voltage measurement pairs 231 in (a) with the same color-coding used 232 to match the illustration. The dotted gray 233 lines represent the exact values of the 234 multiples of $R_{\rm H}$. All regions were on the 235 v = 2 plateau. (c) Several new configura-236 tions were measured and compared with 237 both simulations and the CER formula-238 tion, with the latter two in exact agree-239 ment. Thus, both theoretical values are 240 represented by the same gray dotted line 241 in each of the four panels. On the bottom 242 left of each graph panel, the illustrated 243 device is shown with the corresponding 244 locations of sources (blue plus symbol) 245 and drains (red minus symbol) along the 246 device. Voltages were measured from 247 the point before the sources split to the 248 point after the drains rejoin, yielding the 249 CERs of each configuration. 250



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ods were used to predict the expected CERs of the circuit—the LTspice simulator and the CER formulation. Both methods agreed exactly and are plotted as gray dotted lines for each of the eight configurations. The crucial formula used to mathematically predict the expected CERs⁴⁹ is as follows:

$$q_{N-1}(n_{N-1}) = rac{q_{N-2}(n_{N-1}+1)}{n_{N-1}+rac{q_{N-2}}{q_{1}^{(0)}}}.$$

The CERs calculated in Fig. 3 include the following: $\left\{\frac{6}{7}, \frac{8}{7}, \frac{12}{13}, \frac{4}{3}, \frac{6}{17}, \frac{4}{7}, \frac{3}{4}, \frac{2}{3}\right\}$. Details on how to proceed with the calculation are welldocumented in Ref. 49, and additional examples for some of the configurations in this manuscript are found in the supplementary material.

261 To demonstrate how increasingly complex calculations can 262 yield atypical CERs, devices containing seven pnJs were fabricated as shown in Fig. 4(a). Although even more *pn*Js can be placed along 263 264 the 2 mm length of the device, their number was limited by the preference of accessing each region with an electrical contact for proof 265 266 of concept. Figure 4(a) shows voltage leads of varying color that 267 were used for determining the resistance curves and by extension 268 the CERs [Fig. 4(b)].

Sufficient quantization was seen for the more traditional cases 269 270 of measuring the resistance across parts of the device while the source and drain are at the farthest terminals. All integer multiples of 271 272 R_H between 1 and 8 were accessible in this characterization, warrant-273 ing further measurements with multiple terminals. In Fig. 4(c), four 274 configurations were measured using different numbers of total ter-275 minals. The top panel, using four terminals as illustrated in the inset, 276 yielded data that were then compared to the predicted CER of $q_3 = \frac{8}{9}$ 277 The two middle panels used five terminals and were compared with their corresponding predicted values of $q_4 = \frac{9}{14}$ and $q_4 = \frac{24}{29}$. In the bottom panel, the six-terminal configuration was measured and 278 279 compared with its corresponding prediction of $q_5 = \frac{32}{57}$. For the sake 280 281 of clarity and as an additional tutorial, this fourth case is calculated 282 in more detail in the supplementary material. Overall, such devices and their CERs can be measured for many configurations of similar 283 284 or greater complexity. Moreover, desired, user-specific CERs can be reversed engineered into a corresponding configuration. 285

286 In conclusion, this work pursued further efforts involving pnJ 287 devices fabricated from EG on SiC with junction widths sufficiently 288 narrow to observe usual edge-state propagation. By configuring an 289 experimental setup to include multiple sources and drains, various 290 atypical quantized resistances became accessible and matched pre-291 dicted values based on LTspice simulations. Additionally, recently 292 reported analytical methods were also used to support the predicted 293 values of the same atypical fractions of R_H . The results demonstrate 294 that *pnJs* have the potential to bring scalable resistance values as well as reinforce the validity of the aforementioned CER formula-295 296 tion, which provides a simple algorithm for determining the effective 297 quantized resistances in pnJ circuits.

298 See the supplementary material for the details on UV exposure299 and for additional calculations.

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REFERENCES

(1)

¹A. K. Geim and K. S. Novoselov, Nat. Mater. 6, 183 (2007).

²A. H. Castro Neto, F. Guinea, N. M. R. Peres, K. S. Novoselov, and A. K. Geim, Rev. Mod. Phys. 81, 109 (2009).

³K. S. Novoselov, V. I. Fal'ko, L. Colombo, P. R. Gellert, M. G. Schwab, and K. A. Kim, Nature **490**, 192 (2012).

⁴S. Das Sarma, S. Adam, E. H. Hwang, and E. Rossi, Rev. Mod. Phys. **83**, 407 (2011).

⁵J. R. Williams, L. DiCarlo, and C. M. Marcus, Science 317, 638 (2007).

⁶B. Huard, J. A. Sulpizio, N. Stander, K. Todd, B. Yang, and D. Goldhaber-Gordon, Phys. Rev. Lett. **98**, 236803 (2007).

⁷B. Özyilmaz, P. Jarillo-Herrero, D. Efetov, D. A. Abanin, L. S. Levitov, and P. Kim, Phys. Rev. Lett. **99**, 166804 (2007).

⁸N. N. Klimov, S. T. Le, J. Yan, P. Agnihotri, E. Comfort, J. U. Lee, D. B. Newell, and C. A. Richter, *Phys. Rev. B* **92**, 241301 (2015).

⁹S. W. LaGasse and J. U. Lee, Phys. Rev. B **94**, 165312 (2016).

¹⁰ A. F. Young and P. Kim, Nat. Phys. 5, 222 (2009).

¹¹J. R. Williams, T. Low, M. S. Lundstom, and C. M. Marcus, Nat. Nanotechnol. 6, 222 (2011).

¹²H. Schmidt, J. C. Rode, C. Belke, D. Smirnov, and R. J. Haug, Phys. Rev. B 88, 075418 (2013).

¹³F. Amet, J. R. Williams, K. Watanabe, T. Taniguchi, and D. Goldhaber-Gordon, Phys. Rev. Lett. **112**, 196601 (2014).

¹⁴T. Taychatanapat, J. Y. Tan, Y. Yeo, K. Watanabe, T. Taniguchi, and B. Özyilmaz, Nat. Commun. 6, 6093 (2015).

¹⁵P. Rickhaus, M. H. Liu, P. Makk, R. Maurand, S. Hess, S. Zihlmann, M. Weiss, K. Richter, and C. Schönenberger, Nano Lett. 15, 5819 (2015).

¹⁶N. Kumada, F. D. Parmentier, H. Hibino, D. C. Glattli, and P. Roulleau, Nat. Commun. 6, 8068 (2015).

¹⁷J. Lee, D. Wong, J. Velasco, Jr., J. F. Rodriguez-Nieva, S. Kahn, H.-Z. Tsai, T. Taniguchi, K. Watanabe, A. Zettl, F. Wang, L. S. Levitov, and M. F. Crommie, Nat. Phys. **12**, 1032–1036 (2016).

¹⁸X. Gan, R.-J. Shiue, Y. Gao, I. Meric, T. F. Heinz, K. Shepard, J. Hone, S. Assefa, and D. Englund, Nat. Photonics 7, 883 (2013).

¹⁹Y. Zhao, J. Wyrick, F. D. Natterer, J. F. Rodriguez-Nieva, C. Lewandowski, K. Watanabe, T. Taniguchi, L. S. Levitov, N. B. Zhitenev, and J. A. Stroscio, Science **348**, 672 (2015).

²⁰S. Chen, Z. Han, M. M. Elahi, K. M. Masum Habib, L. Wang, B. Wen, Y. Gao, T. Taniguchi, K. Watanabe, J. Hone, A. W. Ghosh, and C. R. Dean, Science 353, 1522 (2016).

²¹ M. M. Elahi, K. M. Masum Habib, K. Wang, G.-H. Lee, P. Kim, and A. W. Ghosh, Appl. Phys. Lett. **114**, 013507 (2019).

²²V. V. Cheianov, V. Fal'ko, and B. L. Altshuler, Science 315, 1252 (2007).

²³ F. Ghahari, D. Walkup, C. Gutiérrez, J. F. Rodriguez-Nieva, Y. Zhao, J. Wyrick,
 F. D. Natterer, W. G. Cullen, K. Watanabe, T. Taniguchi, L. S. Levitov, N. B.
 Zhitenev, and J. A. Stroscio, Science 356, 845 (2017).

²⁴ J. Fang, D. Wang, C. T. DeVault, T.-F. Chung, Y. P. Chen, A. Boltasseva, V. M. Shalaev, and A. V. Kildishev, Nano Lett. **17**, 57 (2017).

²⁵T. Mueller, F. Xia, and P. Avouris, Nat. Photonics 4, 297 (2010).

²⁶S. Schuler, D. Schall, D. Neumaier, L. Dobusch, O. Bethge, B. Schwarz, M. Krall, and T. Mueller, Nano Lett. 16, 7107 (2016).

²⁷F. Xia, T. Mueller, Y. Lin, A. Valdes-Garcia, and P. Avouris, Nat. Nanotechnol.
 4, 839 (2009).

²⁸A. F. Rigosi and R. E. Elmquist, Semicond. Sci. Technol. 34, 093004 359 (2019).

²⁹T. J. B. M. Janssen, A. Tzalenchuk, R. Yakimova, S. Kubatkin, S. Lara-Avila, S. Kopylov, and V. I. Fal'ko, Phys. Rev. B 83, 233402 (2011).

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Q410

- ³⁰ A. Tzalenchuk, S. Lara-Avila, A. Kalaboukhov, S. Paolillo, M. Syväjärvi, R.
 Yakimova, O. Kazakova, T. J. B. M. Janssen, V. Fal'ko, and S. Kubatkin, Nat.
- 364 Nanotechnol. 5, 186 (2010).
- 365 ³¹ A. F. Rigosi, C.-I. Liu, N. R. Glavin, Y. Yang, H. M. Hill, J. Hu, A. R. Hight
- 366 Walker, C. A. Richter, R. E. Elmquist, and D. B. Newell, ACS Omega 2, 2326 (2017).
- ³²R. Ribeiro-Palau, F. Lafont, J. Brun-Picard, D. Kazazis, A. Michon, F.
 Cheynis, O. Couturaud, C. Consejo, B. Jouault, W. Poirier, and F. Schopfer, Nat.
- 369 Nanotechnol. 10, 965 (2015).
- 370 ³³A. F. Rigosi, N. R. Glavin, C.-I. Liu, Y. Yang, J. Obrzut, H. M. Hill, J. Hu,
- H.-Y. Lee, A. R. Hight Walker, C. A. Richter, R. E. Elmquist, and D. B. Newell,
 Small 13, 1700452 (2017).
- ³⁴ Y. Fukuyama, R. E. Elmquist, L.-I. Huang, Y. Yang, F.-H. Liu, and N.-H.
 Kaneko, IEEE Trans. Instrum. Meas. 64, 1451 (2015).
- 375 ³⁵ A. F. Rigosi, A. R. Panna, S. U. Payagala, M. Kruskopf, M. E. Kraft, G. R. Jones,
- B.-Y. Wu, H.-Y. Lee, Y. Yang, J. Hu, D. G. Jarrett, D. B. Newell, and R. E. Elmquist,
 IEEE Trans. Instrum. Meas. 68, 1870 (2019).
- ³⁶T. Oe, A. F. Rigosi, M. Kruskopf, B.-Y. Wu, H.-Y. Lee, Y. Yang, R. E.
 Elmquist, N.-H. Kaneko, and D. G. Jarrett, IEEE Trans. Instrum. Meas. ■, 1
 (2019).
- ³⁷M. Kruskopf, A. F. Rigosi, A. R. Panna, D. K. Patel, H. Jin, M. Marzano,
- M. Berilla, D. B. Newell, and R. E. Elmquist, IEEE Trans. Electron Devices 66, 3973 (2019).
- ³⁸ M. Kruskopf, A. F. Rigosi, A. R. Panna, M. Marzano, D. K. Patel, H. Jin,
 D. B. Newell, and R. E. Elmquist, Metrologia 56, 065002 (2019).
- ³⁹J. Hu, A. F. Rigosi, J. U. Lee, H.-Y. Lee, Y. Yang, C.-I. Liu, R. E. Elmquist, and
 D. B. Newell, Phys. Rev. B 98, 045412 (2018).
- ⁴⁰ M. Woszczyna, M. Friedmann, T. Dziomba, T. Weimann, and F. J. Ahlers, Appl.
 Phys. Lett. **99**, 022112 (2011).
- ⁴¹ J. Hu, A. F. Rigosi, M. Kruskopf, Y. Yang, B.-Y. Wu, J. Tian, A. R. Panna,
- H.-Y. Lee, S. U. Payagala, G. R. Jones, M. E. Kraft, D. G. Jarrett, K. Watanabe,
 T. Taniguchi, R. E. Elmquist, and D. B. Newell, Sci. Rep. 8, 15018
- (2018).
- ³⁹³ ⁴²D. A. Abanin and L. S. Levitov, Science **317**, 641 (2007).
- ⁴³T. Lohmann, K. von Klitzing, and J. H. Smet, Nano Lett. **9**, 1973 (2009).
- ⁴⁴S. T. Le, J. A. Hagmann, N. Klimov, D. B. Newell, J. U. Lee, J. Yan, and C. A. Richter (submitted).

⁴⁵S. Matsuo, S. Takeshita, T. Tanaka, S. Nakaharai, K. Tsukagoshi, T. Moriyama, T. Ono, and K. Kobayashi, Nat. Commun. 6, 8066 (2015).

⁴⁶C. Kumar, M. Kuiri, and A. Das, Solid State Commun. 270, 38 (2018).

⁴⁷ A. F. Rigosi, D. K. Patel, M. Marzano, M. Kruskopf, H. M. Hill, H. Jin, J. Hu, A. R. Hight Walker, M. Ortolano, L. Callegaro, C.-T. Liang, and D. B. Newell, Carbon 154, 230 (2019).

⁴⁸Commercial equipment, instruments, and materials are identified in this paper in order to specify the experimental procedure adequately. Such identification is not intended to imply recommendation or endorsement by the National Institute of Standards and Technology or the United States government, nor is it intended to imply that the materials or equipment identified are necessarily the best available for the purpose.

⁴⁹A. F. Rigosi, D. K. Patel, M. Marzano, M. Kruskopf, H. M. Hill, H. Jin, J. Hu, R. E. Elmquist, and D. B. Newell, Physica B ■, 411971 (2019).

⁵⁰See www.linear.com/designtools/software/ for Linear Technology 2018 LTspice XVII.

⁵¹ M. Ortolano and L. Callegaro, Meas. Sci. Technol. 26, 085018 (2015).

⁵² M. Kruskopf, D. M. Pakdehi, K. Pierz, S. Wundrack, R. Stosch, T. Dziomba,
 M. Götz, J. Baringhaus, J. Aprojanz, and C. Tegenkamp, 2D Mater. 3, 041002
 (2016).

⁵³V. Panchal, Y. Yang, G. Cheng, J. Hu, M. Kruskopf, C.-I. Liu, A. F. Rigosi, C. Melios, A. R. Hight Walker, D. B. Newell, O. Kazakova, and R. E. Elmquist, Commun. Phys. 1, 83 (2018).

⁵⁴S. Sarkar, H. Zhang, J.-W. Huang, F. Wang, E. Bekyarova, C. N. Lau, and R. C. Haddon, Adv. Mater. 25, 1131 (2013).

⁵⁵J. Dai, Y. Zhao, X. Wu, X. C. Zeng, and J. Yang, J. Phys. Chem. C 117, 22156 (2013).

⁵⁶E. Bekyarova, S. Sarkar, S. Niyogi, M. E. Itkis, and R. C. Haddon, J. Phys. D: Appl. Phys. **45**, 154009 (2012).

⁵⁷S. Che, K. Jasuja, S. K. Behura, P. Nguyen, T. S. Sreeprasad, and V. Berry, Nano Lett. **17**, 4381 (2017).

⁵⁸A, F. Rigosi, M. Kruskopf, H. M. Hill, H. Jin, B.-Y. Wu, P. E. Johnson, S. Zhang, M. Berilla, A. R. Hight Walker, C. A. Hacker, D. B. Newell, and R. E. Elmquist, Carbon 142, 468 (2019).

⁵⁹S. Lara-Avila, K. Moth-Poulsen, R. Yakimova, T. Bjørnholm, V. Fal'ko, A. Tzalenchuk, and S. Kubatkin, Adv. Mater. 23, 878 (2011).

Supplementary Material: Accessing ratios of quantized resistances in graphene *p-n* junction devices using multiple terminals

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- 3. Raman spectra for large scale homogeneity
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1. Device fabrication and UV exposure information

Devices underwent additional fabrication steps after unmodified Hall bar devices were functionalized with $Cr(CO)_3$. The steps are listed below, with the full process illustrated in Fig. 1-SM:^{∂}

1. Spin photoresist at 5000 rpm for 1 min (acceleration: 5000 rpm/s). Photoresist composed of 75 % electronic-grade propylene glycol monomethyl ether acetate, 15 % mixed cresol novolak resin, and 10 % diazo photoactive compound (sold commercially as \$1813 from The Dow Chemical Company).

2. Bake chips at 115 °C for 1 min.

3. Expose to ultraviolet light (365 nm) for 5 seconds, using a photomask designed to expose only the central region of the device, as in Figure 4 (other designs shown later). Parameters were measured on a high-precision mask and bond aligner (sold commercially as the Suss MA6 from Suss Microtec). {1130 W; WEC = cont.; Vacuum mode: 10 s / 30 s / 15 s; Al-gap = $15 \mu \text{m}$; Dosage = 100 mJ}.

4. Use solution of 97 % water, 2.3 % tetramethylammonium hydroxide, and 0.7 % polyglycol (commercially sold as MF-26A Developer from The Dow Chemical Company), for 1 min to remove exposed region.

5. Bake chips at 200 °C for 5 min.

6. Spin solution of 95 % ethyl lactate and 5 % Poly(methyl methacrylate/methacrylic acid) as a spacer layer (sold commercially as EL6 from The Dow Chemical Company). Thickness of this photoresist should be between 50 nm to 100 nm (or less). Spin rate is 5000 rpm (acceleration of 5000 rpm/s).

7. Bake chips at 170 °C for 1 min.

8. Spin photoresist at 4000 rpm for 1 min to get a desired thickness between 300 nm and 400 nm. Photoresist composed of 89 % anisole and 11 % methyl styrene / chloromethyl acrylate copolymer (sold commercially as ZEP 520A from Zeon Chemicals L. P.).

9. Bake chips at 170 °C for 1 min.

10. Expose chips to 254 nm ultraviolet light for approximately 15 hours to activate the p-type regions. This time can be altered based on distance from the sample.

11. Other device regions should be inherently *n*-type. Level of doping can be adjusted by annealing.

12. UV data shown in Figure 2-SM.



Figure 1-SM. A typical Hall bar device, after functionalization, is prepared with various polymers to enable the eventual adjustment of *p*-type and *n*-type regions.



Figure 2-SM. Data of an example UV exposure session. As expected, the *n*-region, protected by a spacer layer of S1813, does not change much with time (initial transient effects aside). The *p*-region does shift after crossing the Dirac point around 7 h to 8 h. The dip at 5.5 h is the result of competing effects from the UV treatment and the device heating due to the UV bulb.

2. Example calculations

Calculations are provided below for three cases presented in the main text (Figs. 3-SM, 4-SM, 5-SM).



Figure 3-SM. The calculation for an example configuration from the main text is provided below. This N = 5 non-alternating configuration has its n_j terms assigned according to the guidelines in Ref. [1].

Once the n_j terms have been assigned, the calculation may begin. Since this is a non-alternating system, the condition of edge state cancellation along the junction marked in green in Fig. 3-SM allows us to treat the whole system as two smaller circuits in parallel. The "unit" terminal on the left gives a coefficient of effective resistance (CER) of 1. For the right branch, as described in Ref. [1], the use of the following equation is warranted:

$$q_{N-1}(n_{N-1}) = \frac{q_{N-2}(n_{N-1}+1)}{n_{N-1} + \frac{q_{N-2}}{q_{N-1}^{(0)}}}$$

(A1)

With $n_1 = 1$, we use the linear form of Eq. (A1), which is $q_2 = (n_1 + 1)$. $q_1 = 2$, and that brings us to $n_2 = 1$. If we apply the iteration in Eq. (A1) again:

$$q_2(n_2) = \frac{q_1(n_2+1)}{n_2 + \frac{q_1}{q_2^{(0)}}} = \frac{2(1+1)}{1 + \frac{2}{1}} = \frac{4}{3}$$

In the main text, the term $q_2^{(0)}$ was not directly addressed since its explanation is provided in Ref. [1]. With our two branches assigned, we can get our final CER as $\left(\frac{1}{1} + \frac{3}{4}\right)^{-1} = \frac{4}{7}$.



FIG. 4-SM. The calculation for this N = 8, non-alternating, example configuration from the main text is provided below. Dotted colored lines indicate the terminals in the various parallel circuits.

Since the next example is also a non-alternating system, the condition of edge state cancellation along various junctions allows us to demarcate four distinct parallel circuits. In Fig. 4-SM, two "unit" terminals in green and orange dotted lines give CERs of 1. The dotted blue and purple configurations are also effectively N = 2 systems with the purple dotted-lined system having $n_1 = 2$ and the blue dotted-lined system having $n_1 = 1$. If one sums all these branches in parallel, then the CER is: $\left(\frac{1}{1} + \frac{1}{1} + \frac{1}{3} + \frac{1}{2}\right)^{-1} = \frac{6}{17}$.



FIG. 5-SM. The calculation for this N = 6 alternating configuration from the main text is provided below. The n_j terms have been assigned according to the guidelines in Ref. [1].

This calculation will be the most involved of the examples. After the n_j terms have been assigned according to the guidelines in Ref. [1], one can begin using Eq. (A1) to begin the iterative algorithm. Since $n_1 = 1$, one obtains $q_2 = (n_1 + 1) = 2$. Next, with $n_2 = 1$:

$$q_2(n_2) = \frac{q_1(n_2+1)}{n_2 + \frac{q_1}{q_2^{(0)}}} = \frac{2(1+1)}{1 + \frac{2}{1}} = \frac{4}{3}$$

Then, with $n_3 = 1$, approaching the next iteration to get q_3 (see Fig. 6-SM) becomes slightly more difficult since the term $q_3^{(0)}$ needs evaluation.



FIG. 6-SM. For subsequent iterations of the calculation for the configuration in Fig. 5-SM, one must focus on smaller subset configurations to determine q_5 mathematically. Here, q_3 is dependent on the term $q_3^{(0)}$, which is the CER for the limiting case where $n_3 = 0$ (see Fig. 7-SM).



FIG. 7-SM. Evaluation for $q_3^{(0)}$ is easier to accomplish with this visual guide. For the limiting case where $n_3 = 0$ (where n_3 is defined in Fig. 6-SM), a "new" configuration must be evaluated. New parameters have been labeled in orange and red. This configuration contains a unit terminal on the right that is isolated from the left branch defined by the parameter \tilde{n}_1 . Therefore, $q_3^{(0)} = \left(\frac{1}{1} + \frac{1}{2}\right)^{-1} = \frac{2}{3}$.

From Fig. 7-SM, we get $q_3^{(0)} = \frac{2}{3}$ since the first parallel branch (unit terminal on right) gives a CER of 1 and the left parallel branch gives a CER of 2. This allows us to get q_3 :

$$q_3(n_3) = \frac{q_2(n_3+1)}{n_3 + \frac{q_2}{q_3^{(0)}}} = \frac{\frac{4}{3}(1+1)}{1 + \frac{4/3}{2/3}} = \frac{8}{9}$$

The next iteration continues with q_4 , where we evaluate the CER of the entire circuit shown in Fig. 8-SM.



FIG. 8-SM. Evaluation continues with q_4 , where this five-terminal configuration must be solved before continuing. The formula contains the term $q_4^{(0)}$, which must first be evaluated before q_4 can be solved.



FIG. 9-SM. Evaluation for $q_4^{(0)}$ requires $n_4 = 0$ (where n_4 is defined in Fig. 8-SM), giving us a "new" configuration to solve here. This configuration contains a unit terminal on the left that is isolated from the right branch defined by the parameters (\double-tilde) n_1 and n_2 .

In Fig. 9-SM, $q_4^{(0)} = \frac{4}{7}$ since it is numerically identical to Fig. 3-SM. This allows us to get q_4 :

$$q_4(n_4) = \frac{q_3(n_4+1)}{n_4 + \frac{q_3}{q_4^{(0)}}} = \frac{\frac{8}{9}(1+1)}{1 + \frac{8}{4}/{7}} = \frac{16}{23}$$

The final iteration ends with q_5 , where we evaluate the CER of the entire circuit shown in Fig. 10-SM.



FIG. 10-SM. Evaluation ends with q_5 , where this six-terminal configuration must be solved for the final answer. The formula contains the term $q_5^{(0)}$, which must first be evaluated before q_5 can be solved.



FIG. 11-SM. Evaluation for $q_5^{(0)}$ requires $n_5 = 0$ (where n_5 is defined in Fig. 10-SM), giving us a "new" configuration to solve here. This configuration contains a unit terminal on the far right that is isolated from the right branch defined by the parameters (\triple-tilde) n_1 , n_2 , and n_3 .

In Fig. 11-SM, $q_5^{(0)}$ is relatively straightforward since there are only two parallel branches: a unit terminal giving a CER of 1 and an alternating four-terminal configuration that is mathematically identical to q_3 , whose CER is $\frac{8}{9}$. This allows us to

get $q_5^{(0)}$: $q_5^{(0)} = \left(\frac{1}{1} + \frac{9}{8}\right)^{-1} = \frac{8}{17}$

$$q_5(n_5) = \frac{q_4(n_5+1)}{n_5 + \frac{q_4}{q_5^{(0)}}} = \frac{\frac{16}{23}(1+1)}{1 + \frac{16}{23}} = \frac{32}{57}$$

The final result is $q_5 = \frac{32}{57}$, and is closely matched by the experimental data in the main text.

3. Raman spectra for large scale homogeneity

In Fig. 12-SM, a Raman map was acquired with a Renishaw InVia micro-Raman spectrometer^[see notes] using a 633 nm wavelength excitation laser source and a backscattering configuration. The spot size was about 1 μ m, the acquisition times were 300 s, the laser power was 1.7 mW power, and the optical path included a 50 × objective and 1200 mm⁻¹ grating. The spread is indicative of a relatively homogeneous sample.



FIG. 12-SM. (a) Optical image of example device after growth. (b) A Raman map was acquired to ensure sample homogeneity. The map was taken over the area shaded in light blue in (a).

4. Supporting AFM images

Prior to deposition of Cr(CO)₃ and the various polymers required for large-scale electron density modulation, AFM images were acquired on post-growth graphene areas to verify homogeneity. The polymer-assisted growth suppressed the formation of nanoscopic steps typically seen in SiC sublimation.



FIG. 13-SM. Example AFM image for approximate region of the device similar to Raman map and taken prior to functionalization. This image verifies the suppression of overactive step bunching typically seen with SiC sublimation. Aside from several spot contaminants, the graphene can grow unimpeded along the ordered steps.

NOTES

^a Commercial equipment, instruments, and materials are identified in this paper in order to specify the experimental procedure adequately. Such identification is not intended to imply recommendation or endorsement by the National Institute of Standards and Technology or the United States government, nor is it intended to imply that the materials or equipment identified are necessarily the best available for the purpose.

REFERENCES

¹A.F. Rigosi, D.K. Patel, M. Marzano, M. Kruskopf, H.M. Hill, H. Jin, J. Hu, A.R. Hight Walker, and D.B. Newell, Physica B, **DOI:** 10.1016/j.physb.2019.411971 (2019).